

Product / Package Information

Package	LFCSP
Body Size (mm)	5 X 5 X 1.45
Lead Count	24
Terminal Finish	100 Sn
MS Number	MS012536A

Environmental Information

RoHS Compliant	Yes with exemption
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	4.69E-02	84.50	845000	60.30		602987
Thermosets	Epoxy & Phenol resin	Proprietary	8.33E-03	15.00	150000	10.70		107039
Other inorganic materials	Carbon black	1333-86-4	2.78E-04	0.50	5000	0.36		3568
Subtotal			5.56E-02	100.00	1000000	71.36		713594

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	1.55 E-02	97.50	975000	19.90		199023
Copper & its alloys	Iron	7439-89-6	3.73 E-04	2.35	23500	0.48		4797
Copper & its alloys	Zinc	7440-66-6	1.91 E-05	0.12	1200	0.02		245
Copper & its alloys	Phosphorus	7723-14-0	4.77 E-06	0.03	300	0.01		61
Subtotal			1.59 E-02	100.00	1000000	20.41		204127

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	2.84 E-04	100.0	1000000	0.36		3646

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	5.18 E-04	100.0	1000000	0.67		6660

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	3.25 E-04	99.0	990000	0.42		4178
Precious metals	Palladium	7440-05-3	3.28 E-06	1.00	10000	0.004		42
Subtotal			3.28 E-04	100.0	1000000	0.42		4220

Chips

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	4.22 E-03	100.0	1000000	5.42		54170

Die Attach 1

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other organic materials	Resin	Proprietary	7.77 E-05	50	500000	0.10		998
Other organic materials	Ethene, tetrafluoro-, homopolymer	9002-84-0	6.99 E-05	45	450000	0.09		898
Other organic materials	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8	7.77 E-06	5	50000	0.01		100
Subtotal			1.55 E-04	100.0	1000000	0.20		1996

Die Attach 2

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other organic materials	Epoxy Resin	Proprietary	1.47 E-05	85	94360	0.02		188
Other organic materials	Acrylic resin	9002-84-0	2.59 E-06	15	16652	0.00		33
Subtotal			1.72 E-05	100.0	111012	0.02		222

Seal Glass

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Ceramics/Glass	Lead borosilicate glass	65997-17-3	7.74 E-04	87.5	875000	0.99		9945
Ceramics/Glass	Aluminosilicate glass	65997-17-3	1.11 E-04	12.5	125000	0.14		1421
Subtotal			8.85 E-04	100.0	1000000	1.14		11365

Package Totals			Weight (g) 7.78 E-02			Percentage (%) 100		PPM 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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